

## Texas Instruments

### Reliability Estimator

	Early life failure rate	MTBF / FIT		Early life failure rate supporting data				MTBF / FIT supporting data						
Part number	ELFR-DPPM	MTBF	FIT	Conf level (%)	Test temp (i½C)	Sample size	Fails	Usage temp (i½C)	Conf level (%)	Activation energy (eV)	Test temp (i½C)	Test duration (hours)	Sample size	Fails
DCR011205P	TBD	1.29 x 10 <sup>8</sup>	7.8	-	-	-	-	55	60.0	0.7	125	1000	1505	0

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